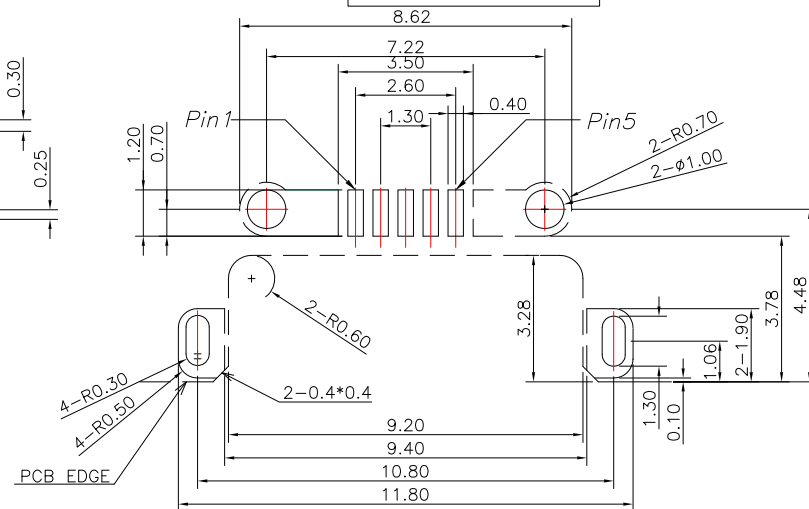
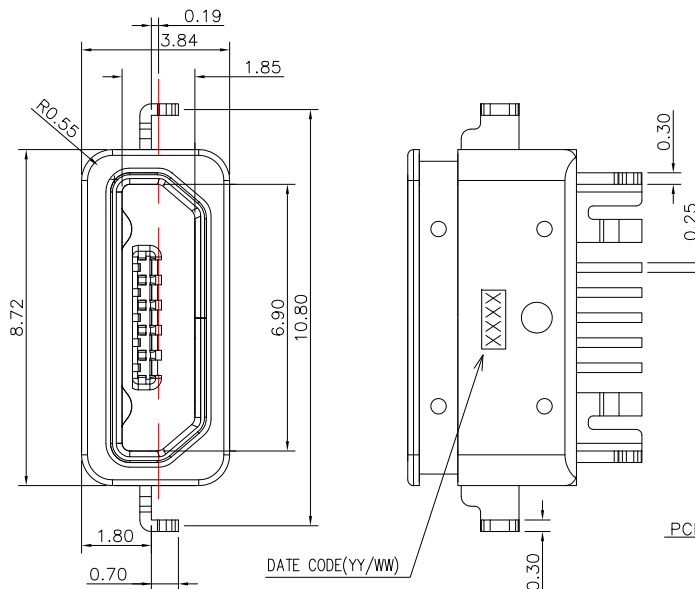
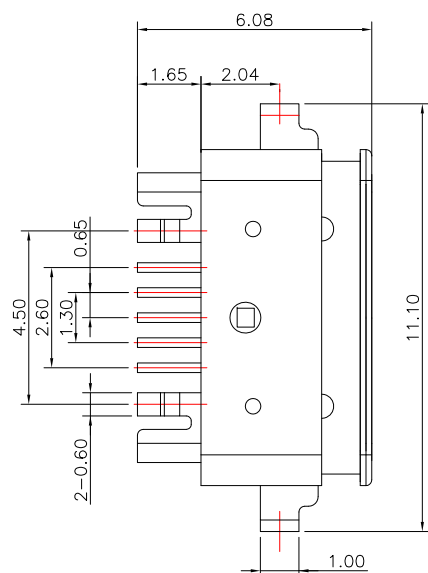
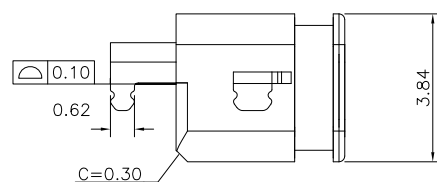


IP67



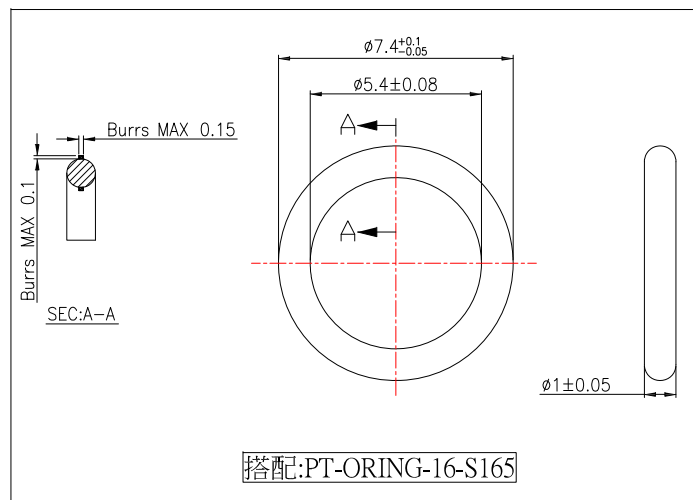
P.C.B LAYOUT MOUNTING PATTERN



MRUSB-5B-WP13-x-S165

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



NOTES:

MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC
- 1.2 CONTACT: COPPER ALLOY
- 1.3 SHELL: SUS
- 1.4 O-RING: SILICON

FINISH:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER
- 3.SPECIFICATION:
 - 3.1 RATING: 1.0A
 - 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 500 VAC
 - 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
 - 3.4 INSULATION RESISTANCE: 1000 MΩ MIN.

5	新增O-RING圖	Jack	102920	CONTACT建倚科技股份有限公司CONTACT TECHNOLOGY CORP. TOLERANCE UNLESS OTHERWISE STATED: Up to 5 ±0.2 Above 5 ~ 15 ±0.3 Above 15 ~ 30 ±0.4 Above 30 ~ 50 ±0.5 Angle ±0.3° 3RD. ANGEL'S  UNITS MM	DRAWN BY: Jack Lu	DATE 10/29/20	MAT'L	TITLE CONNECTOR	7			
5	刪除O-RING圖	Jack	040819		CHECKED BY: Jacky Chen	DATE 10/29/20	FINISH	MODLE MICRO USB 5PF B TYPE 沉板 板上 H 1.8 IP67				
4	更新樣式	Jack	032119		APPROVED BY: Tony Kao	DATE 10/29/20	SCALE 1 : 1	DWG NO. MRUSB-5B-WP13-x-S165		SIZE A4		
3	新增O-RING圖	Jack	112618				SHEET NO. 1 of 1	PART NO. MRUSB-5B-WP13-x-S165		VER R6		
2	新增尺寸	Jack	073118									
1	更新為A0版	Jack	071718									
ITEM NO.	DESCRIPTION	DRAWN	DATE									
A		B		C		D	E	F	G	H	I	J